Product Change Notification: CAAN-25YVIQ071

Date:

29-Oct-2026

Product Category:

Wireless IC

Notification Subject:

CCB 8630 Final Notice: Qualification of MMT as an additional assembly site for selected MICRF219A, MICRF221, MICRF229, MICRF211A, MICRF213, MICRF218, MICRF220 and MICRF230 device families available in 16L QSOP (3.9mm) package.

Affected CPNs:

CAAN-25YVIQ071_Affected_CPN_10292026.pdf
CAAN-25YVIQ071_Affected_CPN_10292026.csv

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of MMT as an additional assembly site for selected MICRF219A, MICRF221, MICRF229, MICRF211A, MICRF213, MICRF218, MICRF220 and MICRF230 device families available in 16L QSOP (3.9mm) package.

Pre and Post Summary Changes:

	Pre Change	**Post Change**		**Change (Yes/No)**
Assembly Site	Unisem (M) Berhad Perak, Malaysia (UNIS)	Unisem (M) Berhad Perak, Malaysia (UNIS)	Microchip Technology Thailand (Branch) (MMT)	Yes
Wire Material	Au	Au	Au	No

	Pre Change		Post Change			Change (Yes/No)
Die Attach Material	84-1LMISR4 (PFAS-free)		84-1LMISR4 (PFAS-free)		QMI519 (PFAS-free)	Yes
Molding Compound Material	G600		G600		G600V	Yes
Lead-Frame Material	A194		A194		A194	No
Lead-Frame Paddle Size	90 x 90 mils	96x130 mils	90 x 90 mils	96x130 mils	100 x 160 mils	Yes
DAP Surface Prep	Ag Spot Plated		Ag Spot Plated		Selective Ag Plating	Yes
Lead-Frame Design	See Pre and Post Change Summary Attachment for Comparison.					

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve on-time delivery performance by qualifying MMT as an additional assembly site.

Change Implementation Status: In Progress

Estimated First Ship Date: 30 November 2026 (date code: 2649)

Note Below EFSD: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	October 2026					November 2026				
Work Week	40	41	42	43	44	45	46	47	48	49
Qual Report Availability					X					
Final PCN Issue Date					X					
Estimated Implementation Date										X

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Note: This is a qualification by similarity (QBS) to CCB 4380 and CCB 6422.

Revision History: October 29, 2026: Issued final notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN_CAAN-25YVIQ071_Pre and Post Change Summary.pdf
PCN_CAAN-25YVIQ071_Qual_Report_CCB4380.pdf
PCN_CAAN-25YVIQ071_Qual_Report_CCB6422.pdf

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our **PCN home page** select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the **PCN FAQ** section.

If you wish to change your PCN profile, including opt out, please go to the **PCN home page** select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

CAAN-25YVIQ071 - CCB 8630 Final Notice: Qualification of MMT as an additional assembly site for selected MICRF219A, MICRF221, MICRF229, MICRF211A, MICRF213, MICRF218, MICRF220 and MICRF230 device families available in 16L QSOP (3.9mm) package.

Affected Catalog Part Numbers (CPN):

MICRF229YQS-HS-TR

MICRF211AYQS-HS-TR

SPN111001Y-TR

MICRF221AYQS

MICRF221AYQS-TR

MICRF229YQS

MICRF229YQS-T5

MICRF229YQS-TR

MICRF211AYQS

MICRF211AYQS-TR

MICRF213AYQS

MICRF213AYQS-TR

MICRF218AYQS

MICRF218AYQS-TR

MICRF219AAYQS

MICRF219AAYQS-TR

MICRF219AYQS

MICRF219AYQS-TR

MICRF220AYQS

MICRF220AYQS-TR

MICRF230YQS

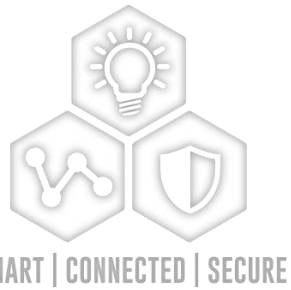
MICRF230YQS-T5

MICRF230YQS-TR

CCB 8630
Pre and Post Change Summary
PCN #: CAAN-25YVIQ071

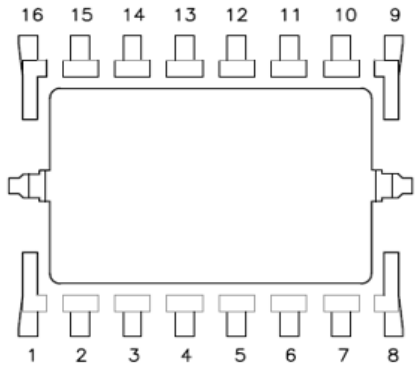


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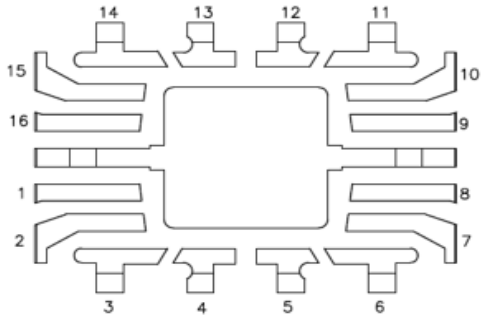


LEAD FRAME COMPARISON

UNIS

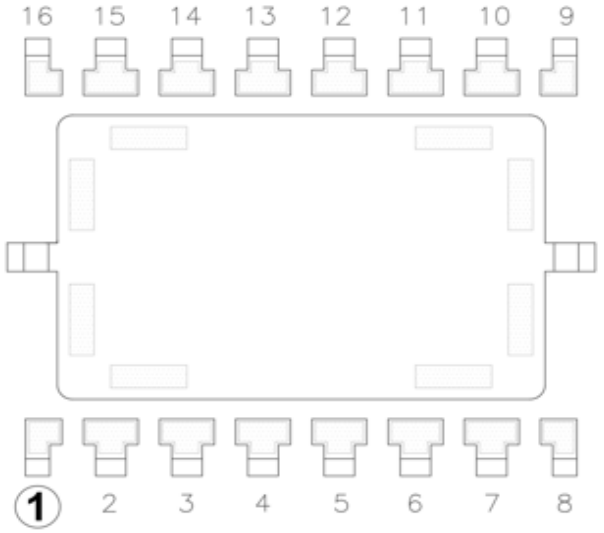


Lead-frame Material	A194
Lead-frame Paddle Size	96x130 mils
DAP Surface Prep	Ag Spot Plated



Lead-frame Material	A194
Lead-frame Paddle Size	90 x 90 mils
DAP Surface Prep	Ag Spot Plated

MMT



Lead-frame Material	A194
Lead-frame Paddle Size	100 x 160 mils
DAP Surface Prep	Selective Ag Plating

Note: Not to scale

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QUALIFICATION REPORT SUMMARY

RELIABILITY LABORATORY

PCN #: CAAN-25YVIQ071

Date:
September 15, 2021

Qualification of MMT as an additional assembly site for selected MICRF219A, MICRF221, MICRF229, MICRF211A, MICRF213, MICRF218, MICRF220 and MICRF230 device families available in 16L QSOP (3.9mm) package. This is Q100 Grade 0 Qualification.

PACKAGE QUALIFICATION REPORT

Purpose: **Qualification of MMT as an additional assembly site for selected MICRF219A, MICRF221, MICRF229, MICRF211A, MICRF213, MICRF218, MICRF220 and MICRF230 device families available in 16L QSOP (3.9mm) package.This is Q100 Grade 0 Qualification.**

CN	ES360303
QUAL ID	R2100684 Rev.A
MP CODE	VXBF1QH5XVA1
Part No.	AA800A_V1R6-01-1416-GLF-13165-TR
Bonding No.	BDM-002687 Rev. A
CCB No.	4380
Package	
Type	16L QSOP
Package size	3.90 mm
Lead Frame	
Paddle size	100 x 160 mils
Material	A194
Surface	Selective Ag Plating
Process	Stamped
Lead Lock	No
Part Number	10101614
Treatment	BOT
Material	
Epoxy	3280
Wire	Au wire
Mold Compound	G600V
Plating Composition	Matte Sn

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PACKAGE QUALIFICATION REPORT

Manufacturing Information:

Assembly Lot No.	Wafer No.	Date Code
MMT-220100914.000	XFML921444577.110	2113G1P
MMT-220200324.000	XFML921444577.110	2114KA6
MMT-220101021.000	XFML921444577.110	2113K14

Result [X] Pass [ ] Fail [ ] _____

16L QSOP (3.90 mm) assembled by MMT pass reliability test per QCI-39000. This package was qualified the Moisture/Reflow Sensitivity Classification Level 1 at 260°C reflow temperature per IPC/JEDEC J-STD-020E standard.

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS	Result	Remarks
Precondition Prior Perform Reliability Tests (At MSL Level 1)	**Electrical Test:** +25°C, 85°C, 125°C and 150°C System: TMT	JESD22-A113	693(0)	693		Good Devices
	Bake 150°C, 24 hrs System: CHINEE	JIP/ IPC/JEDEC J-STD-020E		693		
	85°C/85%RH Moisture Soak 168 hrs. System: TABAI ESPEC Model PR-3SPH			693		
	3x Convection-Reflow 265°C max System: Vitronics Soltec MR1243			693		
	Electrical Test: +25°C, 85°C, 125°C and 150°C System: TMT			0/693	Pass	

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
Temp Cycle	**Stress Condition:** -55°C to +150°C, 2000 Cycles System: TABAI ESPEC TSA-70H	JESD22-A104		231		Parts had been pre-conditioned at 260°C
	Electrical Test: +85°C, 125°C and 150°C System: TMT		231(0)	0/231	Pass	77 units / lot
	Bond Strength: Wire Pull (> 2.5 grams)		15 (0)	0/15	Pass	
	Bond Shear (>15.00 grams)		15 (0)	0/15	Pass	
UNBIASED-HAST	**Stress Condition:** +130°C/85%RH, 96 hrs. System: HAST 6000X	JESD22-A118		231		Parts had been pre-conditioned at 260°C
	Electrical Test: +25°C System: TMT		231(0)	0/231	Pass	77 units / lot
HAST	**Stress Condition:** +130°C/85%RH, 96 hrs. **Bias Volt:** 5.6 Volts System: HAST 6000X	JESD22-A110		231		Parts had been pre-conditioned at 260°C
	Electrical Test: +25°C, 85°C, 125°C and 150°C System: TMT		231(0)	0/231	Pass	77 units / lot

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
High Temperature Storage Life	**Stress Condition:** Bake 175°C, 1000 hrs System: SHEL LAB **Electrical Test:** +25°C, 85°C, 125°C and 150°C System: TMT	JESD22-A103	 45(0)	45 0/45	 Pass	45 units
Solderability **Temp 215°C**	**Steam Aging:** Temp 93°C,8Hrs System: SAS-3000 Solder Dipping: Solder Temp.215°C Solder material: SnPb Sn63, Pb37 System: ERSA RA 2200D Visual Inspection: External Visual Inspection	J-STD-002	22 (0)	22 22 0/22	 Pass	
Solderability **Temp 245°C**	**Steam Aging:** Temp 93°C,8Hrs System: SAS-3000 Solder Dipping: Solder Temp.245°C Solder material: Pb Free Sn 95.5Ag3.9 Cu0.6 System: ERSA RA 2200D Visual Inspection: External Visual Inspection	J-STD-002	22 (0)	22 22 0/22	 Pass	
Physical Dimensions	Physical Dimension, 10 units from 1 lot	JESD22-B100/B108	30(0) Units	0/30	Pass	
Bond Strength Data Assembly	Wire Pull (> 4.00 grams) Bond Shear (> 18.00 grams)	Mil. Std. 883-2011 CDF-AEC-Q100-001	30 (0) Wires 30 (0) bonds	0/30 0/30	Pass Pass	

QUALIFICATION REPORT SUMMARY

RELIABILITY LABORATORY

PCN #: CAAN-25YVIQ071

Date:
November 15, 2024

Qualification of MMT as an additional assembly site for selected MICRF219A, MICRF221, MICRF229, MICRF211A, MICRF213, MICRF218, MICRF220 and MICRF230 device families available in 16L QSOP (3.9mm) package.

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PACKAGE QUALIFICATION REPORT

Purpose	Qualification of MMT as an additional assembly site for selected MICRF219A, MICRF221, MICRF229, MICRF211A, MICRF213, MICRF218, MICRF220 and MICRF230 device families available in 16L QSOP (3.9mm) package.
CN	E000238835
QUAL ID	R2401147 Rev. A
MP CODE	MV0034D3XFX6
Part No.	PIC16F18426-E/SL
Bonding No.	BD-001882 Rev. 02
CCB No.	6422
Package	
Type	14L SOIC
Package size	.150”
Lead Frame	
Paddle size	95 x 155 mils
Material	CDA194
Surface	Selective Ag Plating
Process	Stamped
Lead Lock	No
Part Number	10101416
Treatment	BOT
Material	
Epoxy	QMI519
Wire	CuPdAu wire
Mold Compound	G600V
Plating Composition	Matte Sn

MICROCHIP

PACKAGE QUALIFICATION REPORT

Manufacturing Information:

Assembly Lot No.	Wafer Lot No.	Date Code
MMT-251800673.000	GRSM424422913.220	2431PPE
MMT-251800677.000	GRSM424422913.220	2431DC5
MMT-251901323.000	GRSM424422913.220	2432DD3

Result [X] Pass [ ] Fail [ ] _____

14L SOIC (.150”) assembled by MMT pass reliability test per QCI-39000. This package was qualified the Moisture/Reflow Sensitivity Classification Level 1 at 260°C reflow temperature per IPC/JEDEC J-STD-020E standard.

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS	Result	Remarks
Precondition Prior Perform Reliability Tests (At MSL Level 1)	**Electrical Test:** +25°C and 125°C System: J750	JESD22-A113	693(0)	0/693		Good Devices
	Bake 150°C, 24 hrs. System: CHINEE	JIP/ IPC/JEDEC J-STD-020E		693		
	85°C/85%RH Moisture Soak 168 hrs. System: TABAI ESPEC Model PR-3SPH			693		
	3x Convection-Reflow 265°C max System: Vitronics Soltec MR1243			693		
	Electrical Test: +25°C and 125°C System: J750		693(0)	0/693	Pass	

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
Temp Cycle	**Stress Condition:** -65°C to +150°C, 500 Cycles System: TABAI ESPEC TSA-70H	JESD22-A104		0/231		Parts had been pre-conditioned at 260°C
	Electrical Test: + 125°C System: J750		231(0)	0/231	Pass	77 units / lot
	Bond Strength: Wire Pull (>2.50 grams)		15(0)	0/15	Pass	
UNBIASED-HAST	**Stress Condition:** +130°C/85%RH, 96 hrs. System: HAST 6000X	JESD22-A118		0/231		Parts had been pre-conditioned at 260°C
	Electrical Test: +25°C System: J750		231(0)	0/231	Pass	77 units / lot
HAST	**Stress Condition:** +130°C/85%RH, 96 hrs. **Bias Volt:** 5.5 Volts System: HAST 6000X	JESD22-A110		0/231		Parts had been pre-conditioned at 260°C
	Electrical Test: +25°C and 125°C System: J750		231(0)	0/231	Pass	77 units / lot

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
High Temperature Storage Life	**Stress Condition:** Bake 175°C, 504 hrs. System: TPS Bake Oven **Electrical Test:** +25°C and 125°C System: J750	JESD22-A103	 135(0)	0/135 0/135	 Pass	45 units
Wire sweep	Wire sweep Inspection 15 Wires / lot	-	45(0) Wires	0/45	Pass	
Bond Strength **Data Assembly**	Wire Pull (>2.50 grams) Bond Shear (>15.00 grams)	Mil. Std. 883-2011 CDF-AEC-Q100-001	30(0) Wires 30(0) bonds	0/30 0/30	Pass Pass	